

Title (en)

METHOD FOR TRANSFERRING A CIRCUIT TO A GROUNDING PLANE

Title (de)

VERFAHREN ZUM TRANSFER EINER SCHALTUNG ZU EINER MASSEVERBINDUNGSEBENE

Title (fr)

PROCEDE DE REPORT D'UN CIRCUIT SUR UN PLAN DE MASSE

Publication

EP 1829100 A1 20070905 (FR)

Application

EP 05848368 A 20051222

Priority

- FR 2005051139 W 20051222
- FR 0453229 A 20041224

Abstract (en)

[origin: FR2880189A1] The method involves producing a part of a circuit in or on a surface layer (2) of a substrate, where the substrate comprises a layer (4) buried under the surface layer and an underlying layer utilized in the form of a support. The substrate is transferred to a handle substrate. The underlying layer is removed, and a bonding layer (12) e.g. amorphous silicon layer, is formed on an electrically conductive or a grounding plane forming layer (14). The layer has a thickness of 100 nm. An assembly is transferred to a substrate (30), and the handle substrate is removed.

IPC 8 full level

H01L 21/762 (2006.01)

CPC (source: EP KR US)

H01L 21/762 (2013.01 - KR); **H01L 21/76256** (2013.01 - EP US); **H01L 27/12** (2013.01 - KR)

Citation (search report)

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